
2. This document and related artwork are computer generated. Changes are to be performed on the original database in section 383.

3. Solder components using lead-free solder, item 3.

4. Clean solder flux from board so that there is no discernable residue.

5. X-ray and inspect BGA (U22) solder joints per IPC-7095A.

6. Mark or inkstamp in location shown with 1.0 minimum high characters, the dash number, revision letter, and serial number, "Nxxxxx" (where N is a vendor designation letter assigned by TMT and XXXXX is a unique 5 digit serial number for each part. The vendor designation and the starting serial number shall be in accordance with the values provided in the purchase order), using ink, item 2. Characters to be 1 mm high minimum.

7. For electronics parts list see PL10398535.

8. For schematic diagram see JPL drawing 10398535.

9. This printed wiring assembly consists of both surface mount and through-hole technology.